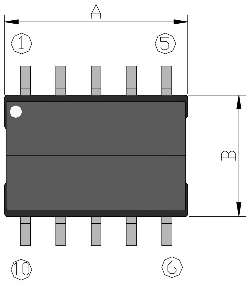
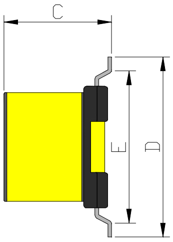
Product Series Code	**GTX**	Brand	GOTREND
File Version	GTX-EP13P-S10B-V1R6	Editor	Terry
Established Date	2013.06.13	Description	2.1A 12V SMD Transformer
Latest Edit Date	2017.02.22	Pages	Page : 2

DIMENSION : [mm]

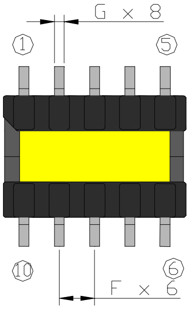
Front View

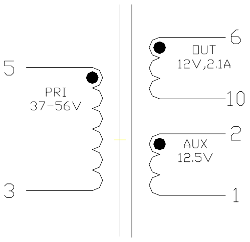


Side View



Bottom View





A [max.]	B [max.]	C [max.]	D[max.]	E+/-0.2	F [+/-0.15]	G [ref.]
15.0	14.5	13.0	20.0	14.5	2.5	0.7

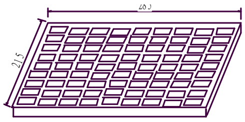
NO	WINDING	TERMINAL	
1	N1	5-----A	
2	N2	6-----10	
3	N3	2-----1	
4	N4	A-----3	
MATERIAL			
DESCRIPTION	**MATERIAL**	**MANUFACTURER**	**UL NO.**
CORE	HP40	ACME or EQU	
BOBBIN	PM9630	TRANSFORMER BOBBIN INDUSTRIAL CO., LTD.	E41429(M)
WIRE	Grad1 P180	ELEKTRISOLA HANGZHOU CO.,LTD or EUQIV	E258243
TAPE	# 1350	3M or EQU	E17385
TUBE	BC346A	JOHN C DOLPH or EQU	E317427
Electrical Characteristics			
ELEC. SPEC			
L (5 - 3) (1KHz / 0.3V)	**DCR (5 - 3)**		
38 uH +/-10%	180.0 mOhm Max.		
TEST CONTITION			
1. LCR meter HP4284 / 42841A			
2. Operating Temperature : -40^{o}C~ ＋85^{o}C			
3.Breakdown Voltage 1 : 8 = Vac 3600 Vrms 2 Sec.			

Reliability Test Result :

<table>
<tr><th>NO</th><th>ITEM</th><th>TEST CONDITIONS</th><th>REMARKS</th></tr>
<tr><td>1</td><td>Thermal Shock
(Temperature Cycle)
溫度循環試驗</td><td>Temperature:-40 ° C/ +85 ° C kept stabilized for 30 minutes each
Cycle: 100 Cycles</td><td>There must be no deformation or change in dimension. Inductance must not change more than the stated tolerance.</td></tr>
<tr><td>2</td><td>Humidity Resistance
耐濕試驗</td><td>Humidity: 90%~ 95% RH
Temperature: 40± 2 ° C
Test Time: 500± 12 Hours</td><td>There must be no case deformation or change in dimensions. Inductance must as specification stated.</td></tr>
<tr><td>3</td><td>HighTemperature
耐熱試驗</td><td>Temperature: 85± 2 ° C
Humidity: 20%
Test Time: 500± 12 Hours</td><td>There must be no case deformation or change in dimensions. Inductance must as specification stated.</td></tr>
<tr><td>4</td><td>Low Temperature
耐寒試驗</td><td>Temperature: -40 ± 2 ° C
Test Time: 500± 12 Hours</td><td>There must be no case deformation or change in dimensions. Inductance must as specification stated.</td></tr>
<tr><td>5</td><td>Temperature and Humidity Cycle
溫/濕度循環試驗</td><td><table>
<tr><th>Step</th><th>Temp</th><th>Humidity</th><th>Time</th></tr>
<tr><td>1</td><td>25± 2 ° C</td><td>95~100%RH</td><td>3.0Hr</td></tr>
<tr><td>2</td><td>55± 2 ° C</td><td>95~96%RH</td><td>9.5Hr</td></tr>
<tr><td>3</td><td>25± 2 ° C</td><td>95~100%RH</td><td>9.5Hr</td></tr>
</table></td><td>There must be no case deformation or change in dimensions. Inductance must as specification stated.</td></tr>
<tr><td>6</td><td>Vibration
振動性試驗</td><td>Frequency: 10Hz~50Hz
Amplitude: 1.5mm
Direction: X,Y,Z
Time: 2 Hours each</td><td>Solder inductors on the test PCB.After vibration, there must be no deformation or change in dimension. Inductance must not change more than the stated tolerance.</td></tr>
<tr><td>7</td><td>IR Reflow Soldering
焊錫性試驗</td><td>Solder: H63A(eutectic solder)
Solder Temp.: 232± 5 ° C
Time: 6 minutes
Cycles: x 1</td><td>Inductance shall be within ± 20% of the initial value.
DCR value shall be within ± 20% of the initial value.</td></tr>
<tr><td>8</td><td>Soldering Heat Resistance
耐熱 焊性試驗</td><td>Preheat:120 ~ 150 ° C (60 sec)
Solder:H63A(eutectic solder)
Solder Temp.: 260 ± 5 ° C
Flux: Rosin
Dip time: 10± 1 seconds</td><td>The chip must have no cracks.More than 75% of the terminal electrode must be covered with solder.
For 96.5 Sn / 3.5 Ag Solder Past: > 217 ° C / 90 Seconds.
For 63.0 Sn / 37 Pb Solder Past: > 183 ° C / 120 Seconds.</td></tr>
</table>

BOX Package : cm

產品裝于90格吸塑盤內，每盤上覆10mm REF 厚度的珍珠棉



每11盤吸塑盤裝于一箱，共900PCS/箱